

### ANY-FREQUENCY PRECISION CLOCK MULTIPLIER/JITTER **ATTENUATOR**

#### **Features**

- to 945 MHz and select frequencies to 1.4 GHz from an input frequency of ■ 2 kHz to 710 MHz
- Ultra-low jitter clock outputs with jitter generation as low as 0.3 ps rms (50 kHz-80 MHz)
- Integrated loop filter with selectable loop bandwidth (60 Hz to 8.4 kHz)
- Meets OC-192 GR-253-CORE jitter specifications
- Dual clock inputs with manual or automatically controlled hitless switching (LVPECL, LVDS, CML, CMOS)

- Generates any frequency from 2 kHz Dual clock outputs with selectable signal format
  - Support for ITU G.709 and custom FEC ratios (255/238, 255/237, 255/236)
  - LOL, LOS, FOS alarm outputs
  - Digitally-controlled output phase adjustment
  - I<sup>2</sup>C or SPI programmable
  - On-chip voltage regulator for 1.8 ±5%, 2.5 ±10%, or 3.3 V ±10% operation
  - Small size: 6 x 6 mm 36-lead QFN
  - Pb-free, ROHS compliant



### **Applications**

- SONET/SDH OC-48/OC-192/STM- 16/STM-64 line cards
- ITU G.709 and custom FEC line
- GbE/10GbE, 1/2/4/8/10G Fibre Channel line cards
- GbE/10GbE Synchronous Ethernet ■
- Optical modules
- Wireless basestations

- Test and measurement
- Broadcast video

# Data converter clocking PDH clock synthesis

#### **Pin Assignments** VDD GND <u>6</u> 36 35 34 33 32 31 30 29 28 RST 27 SDI 26 A2\_SS NC INT\_C1B 3 25 A1 24 A0 C2B 4 GND VDD 5 23 SDA\_SDO Pad 22 SCL XB 7 21 CS\_CA 20 INC GND 8 19 DEC 10 11 12 13 14 15 16 17 18

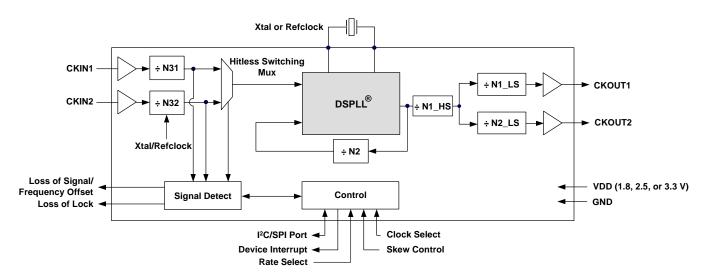
### **Description**

The Si5326 is a jitter-attenuating precision clock multiplier for applications requiring sub 1 ps jitter performance. The Si5326 accepts two input clocks ranging from 2 kHz to 710 MHz and generates two output clocks ranging from 2 kHz to 945 MHz and select frequencies to 1.4 GHz. The two outputs are divided down separately from a common source.

The Si5326 can also use its crystal oscillator as a clock source for frequency synthesis. The device provides virtually any frequency translation combination across this operating range. The Si5326 input clock frequency and clock multiplication ratio are programmable through an I<sup>2</sup>C or SPI interface.

The Si5326 is based on Skyworks Solutions' 3rd-generation DSPLL® technology, which provides frequency synthesis and jitter attenuation in a highly integrated PLL solution that eliminates the need for external VCXO and loop filter components. The DSPLL loop bandwidth is digitally programmable, providing jitter performance optimization at the application level. Operating from a single 1.8, 2.5, or 3.3 V supply, the Si5326 is ideal for providing clock multiplication and jitter attenuation in high performance timing applications.

### **Functional Block Diagram**



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### 1. Electrical Specifications

**Table 1. Recommended Operating Conditions** 

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Ambient Temperature	T <sub>A</sub>		-40	25	85	С
Supply Voltage during	$V_{DD}$	3.3 V Nominal	2.97	3.3	3.63	V
Normal Operation		2.5 V Nominal	2.25	2.5	2.75	V
		1.8 V Nominal	1.71	1.8	1.89	V

**Note:** All minimum and maximum specifications are guaranteed and apply across the recommended operating conditions. Typical values apply at nominal supply voltages and an operating temperature of 25 °C unless otherwise stated.

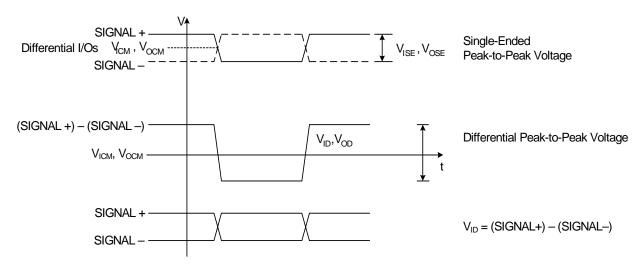


Figure 1. Differential Voltage Characteristics

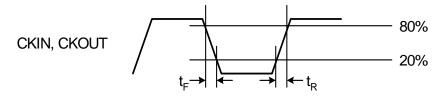


Figure 2. Rise/Fall Time Characteristics

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**Table 2. DC Characteristics** 

 $(V_{DD} = 1.8 \pm 5\%, 2.5 \pm 10\%, \text{ or } 3.3 \text{ V } \pm 10\%, T_A = -40 \text{ to } 85 \text{ °C})$ 

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Supply Current <sup>1</sup>	I <sub>DD</sub>	LVPECL Format 622.08 MHz Out Both CKOUTs Enabled	_	251	279	mA
		LVPECL Format 622.08 MHz Out 1 CKOUT Enabled	_	217	243	mA
		CMOS Format 19.44 MHz Out Both CKOUTs Enabled	_	204	234	mA
		CMOS Format 19.44 MHz Out 1 CKOUT Enabled	_	194	220	mA
		Disable Mode	_	165	_	mA
CKINn Input Pins <sup>2</sup>						
Input Common Mode Voltage (Input Thresh-	V <sub>ICM</sub>	1.8 V ± 5%	0.9	_	1.4	V
old Voltage)		2.5 V ± 10%	1	_	1.7	V
		3.3 V ± 10%	1.1	_	1.95	V
Input Resistance	CKN <sub>RIN</sub>	Single-ended	20	40	60	kΩ
Single-Ended Input Voltage Swing	V <sub>ISE</sub>	f <sub>CKIN</sub> < 212.5 MHz See Figure 1.	0.2	_	_	V <sub>PP</sub>
(See Absolute Specs)		f <sub>CKIN</sub> > 212.5 MHz See Figure 1.	0.25	_	_	$V_{PP}$
Differential Input Voltage Swing	V <sub>ID</sub>	f <sub>CKIN</sub> < 212.5 MHz See Figure 1.	0.2	_	_	$V_{PP}$
(See Absolute Specs)		fCKIN > 212.5 MHz See Figure 1.	0.25	_		$V_{PP}$
Output Clocks (CKOU	Tn) <sup>3</sup>					
Common Mode	CKO <sub>VCM</sub>	LVPECL 100 Ω load line- to-line	V <sub>DD</sub> – 1.42	_	V <sub>DD</sub> -1.25	V

- 1. Current draw is independent of supply voltage
- 2. No under- or overshoot is allowed.
- 3. LVPECL outputs require nominal  $V_{DD} \ge 2.5 \text{ V}$ .
- **4.** This is the amount of leakage that the 3-Level inputs can tolerate from an external driver. See Si53xx Family Reference Manual for more details.
- 5. LVPECL, CML, LVDS and low-swing LVDS measured with Fo = 622.08 MHz.

### Table 2. DC Characteristics (Continued)

 $(V_{DD} = 1.8 \pm 5\%, 2.5 \pm 10\%, \text{ or } 3.3 \text{ V } \pm 10\%, T_A = -40 \text{ to } 85 \text{ °C})$ 

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Differential Output Swing	CKO <sub>VD</sub>	LVPECL 100 $\Omega$ load lineto-line	1.1	_	1.9	V <sub>PP</sub>
Single Ended Output Swing	CKO <sub>VSE</sub>	LVPECL 100 $\Omega$ load lineto-line	0.5	_	0.93	V <sub>PP</sub>
Differential Output Voltage	CKO <sub>VD</sub>	CML 100 $\Omega$ load line-to-line	350	425	500	$mV_PP$
Common Mode Output Voltage	CKO <sub>VCM</sub>	CML 100 $\Omega$ load line-to-line	_	V <sub>DD</sub> -0.36	_	V
Differential Output Voltage	CKO <sub>VD</sub>	LVDS 100 $\Omega$ load line-to-line	500	700	900	$mV_PP$
		Low Swing LVDS 100 $\Omega$ load line-to-line	350	425	500	$mV_PP$
Common Mode Output Voltage	CKO <sub>VCM</sub>	LVDS 100 $\Omega$ load line-to-line	1.125	1.2	1.275	V
Differential Output Resistance	CKO <sub>RD</sub>	CML, LVPECL, LVDS	_	200	_	Ω
Output Voltage Low	CKO <sub>VOLLH</sub>	CMOS	_		0.4	V
Output Voltage High	CKO <sub>VOHLH</sub>	V <sub>DD</sub> = 1.71 V CMOS	0.8 x V <sub>DD</sub>	_	_	V

- 1. Current draw is independent of supply voltage
- 2. No under- or overshoot is allowed.
- LVPECL outputs require nominal V<sub>DD</sub> ≥ 2.5 V.
   This is the amount of leakage that the 3-Level inputs can tolerate from an external driver. See Si53xx Family Reference Manual for more details.
- 5. LVPECL, CML, LVDS and low-swing LVDS measured with Fo = 622.08 MHz.

**Table 2. DC Characteristics (Continued)** 

 $(V_{DD} = 1.8 \pm 5\%, 2.5 \pm 10\%, \text{ or } 3.3 \text{ V } \pm 10\%, T_A = -40 \text{ to } 85 \text{ °C})$ 

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Output Drive Current (CMOS driving into	CKO <sub>IO</sub>	ICMOS[1:0] =11 V <sub>DD</sub> = 1.8 V	_	7.5	_	mA
CKO <sub>VOL</sub> for output low or CKO <sub>VOH</sub> for output high. CKOUT+ and CKOUT- shorted externally)		ICMOS[1:0] =10 V <sub>DD</sub> = 1.8 V	_	5.5	_	mA
		ICMOS[1:0] =01 V <sub>DD</sub> = 1.8 V	_	3.5	_	mA
		ICMOS[1:0] =00 V <sub>DD</sub> = 1.8 V	_	1.75	_	mA
		ICMOS[1:0] =11 V <sub>DD</sub> = 3.3 V	_	32	_	mA
		ICMOS[1:0] =10 V <sub>DD</sub> = 3.3 V	_	24	_	mA
		ICMOS[1:0] =01 V <sub>DD</sub> = 3.3 V	_	16	_	mA
		ICMOS[1:0] =00 V <sub>DD</sub> = 3.3 V	_	8	_	mA
2-Level LVCMOS Input	t Pins		·			•
Input Voltage Low	V <sub>IL</sub>	V <sub>DD</sub> = 1.71 V	_	_	0.5	V
		V <sub>DD</sub> = 2.25 V	_	_	0.7	V
		V <sub>DD</sub> = 2.97 V	_	_	0.8	V
Input Voltage High	V <sub>IH</sub>	V <sub>DD</sub> = 1.89 V	1.4	_	_	V
		V <sub>DD</sub> = 2.25 V	1.8	_	_	V
		V <sub>DD</sub> = 3.63 V	2.5	_	_	V

- 1. Current draw is independent of supply voltage
- 2. No under- or overshoot is allowed.
- 3. LVPECL outputs require nominal V<sub>DD</sub> ≥ 2.5 V.
   4. This is the amount of leakage that the 3-Level inputs can tolerate from an external driver. See Si53xx Family Reference Manual for more details.
- 5. LVPECL, CML, LVDS and low-swing LVDS measured with Fo = 622.08 MHz.

### Table 2. DC Characteristics (Continued)

 $(V_{DD} = 1.8 \pm 5\%, 2.5 \pm 10\%, \text{ or } 3.3 \text{ V } \pm 10\%, T_A = -40 \text{ to } 85 \text{ °C})$ 

Parameter	Symbol	<b>Test Condition</b>	Min	Тур	Max	Unit
3-Level Input Pins <sup>4</sup>					•	
Input Voltage Low	V <sub>ILL</sub>		_	_	0.15 x V <sub>DD</sub>	V
Input Voltage Mid	V <sub>IMM</sub>		0.45 x V <sub>DD</sub>	_	0.55 x V <sub>DD</sub>	V
Input Voltage High	V <sub>IHH</sub>		0.85 x V <sub>DD</sub>		_	V
Input Low Current	I <sub>ILL</sub>	See Note 4	-20	_	_	μA
Input Mid Current	I <sub>IMM</sub>	See Note 4	-2	_	+2	μΑ
Input High Current	ІІНН	See Note 4	_	_	20	μA
LVCMOS Output Pins						
Output Voltage Low	V <sub>OL</sub>	IO = 2 mA V <sub>DD</sub> = 1.71 V		_	0.4	V
Output Voltage Low		IO = 2 mA V <sub>DD</sub> = 2.97 V	_	_	0.4	V
Output Voltage High	V <sub>OH</sub>	IO = -2 mA V <sub>DD</sub> = 1.71 V	V <sub>DD</sub> – 0.4		_	V
Output Voltage High		IO = -2  mA $V_{DD} = 2.97 \text{ V}$	V <sub>DD</sub> – 0.4	_	_	V
Disabled Leakage Current	I <sub>OZ</sub>	RSTb = 0	-100		100	μΑ

- 1. Current draw is independent of supply voltage
- 2. No under- or overshoot is allowed.
- LVPECL outputs require nominal V<sub>DD</sub> ≥ 2.5 V.
   This is the amount of leakage that the 3-Level inputs can tolerate from an external driver. See Si53xx Family Reference Manual for more details.
- 5. LVPECL, CML, LVDS and low-swing LVDS measured with Fo = 622.08 MHz.

**Table 3. Microprocessor Control** 

 $(V_{DD} = 1.8 \pm 5\%, 2.5 \pm 10\%, \text{ or } 3.3 \text{ V} \pm 10\%, T_A = -40 \text{ to } 85 \text{ °C})$ 

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
I <sup>2</sup> C Bus Lines (SDA, S	CL)					
Input Voltage Low	VIL <sub>I2C</sub>		_	_	0.25 x V <sub>DD</sub>	V
Input Voltage High	VIH <sub>I2C</sub>		0.7 x V <sub>DD</sub>	_	V <sub>DD</sub>	V
Input Current	II <sub>I2C</sub>	$VIN = 0.1 \times V_{DD}$ to 0.9 x V <sub>DD</sub>	-10	_	10	μΑ
Hysteresis of Schmitt trigger inputs	VHYS <sub>I2C</sub>	V <sub>DD</sub> = 1.8V	0.1 x V <sub>DD</sub>	_	_	V
990		V <sub>DD</sub> = 2.5 or 3.3 V	0.05 x V <sub>DD</sub>	_	_	V
Output Voltage Low	VOL <sub>I2C</sub>	V <sub>DD</sub> = 1.8 V IO = 3 mA	_	_	0.2 x V <sub>DD</sub>	V
		V <sub>DD</sub> = 2.5 or 3.3 V IO = 3 mA	_	_	0.4	V

## Si5326

Table 3. Microprocessor Control (Continued) (V<sub>DD</sub> = 1.8  $\pm$  5%, 2.5  $\pm$ 10%, or 3.3 V  $\pm$ 10%, T<sub>A</sub> = -40 to 85 °C)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
SPI Specifications				•		
Duty Cycle, SCLK	t <sub>DC</sub>	SCLK = 10 MHz	40	_	60	%
Cycle Time, SCLK	t <sub>c</sub>		100	_	_	ns
Rise Time, SCLK	t <sub>r</sub>	20–80%	_	_	25	ns
Fall Time, SCLK	t <sub>f</sub>	20–80%	_	_	25	ns
Low Time, SCLK	t <sub>lsc</sub>	20–20%	30	_	_	ns
High Time, SCLK	t <sub>hsc</sub>	80–80%	30	_	_	ns
Delay Time, SCLK Fall to SDO Active	t <sub>d1</sub>		_	_	25	ns
Delay Time, SCLK Fall to SDO Transition	t <sub>d2</sub>		_	_	25	ns
Delay Time, SS Rise to SDO Tri-state	t <sub>d3</sub>		_	_	25	ns
Setup Time, SS to SCLK Fall	t <sub>su1</sub>		25	_	_	ns
Hold Time, SS to SCLK Rise	t <sub>h1</sub>		20	_	_	ns
Setup Time, SDI to SCLK Rise	t <sub>su2</sub>		25	_	_	ns
Hold Time, SDI to SCLK Rise	t <sub>h2</sub>		20	_	_	ns
Delay Time between Slave Selects	t <sub>cs</sub>		25	_	_	ns

Table 4. AC Specifications ( $V_{DD}$  = 1.8 ± 5%, 2.5 ±10%, or 3.3 V ±10%,  $T_A$  = -40 to 85 °C)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Single-Ended Referen	ce Clock Inp	ut Pin XA (XB with cap to G	iND)	1		1
Input Resistance	XA <sub>RIN</sub>	RATE[1:0] = LM, ML, MH, or HM, ac coupled	_	12	_	kΩ
Input Voltage Swing	XA <sub>VPP</sub>	RATE[1:0] = LM, ML, MH, or HM, ac coupled	0.5	_	1.2	V <sub>PP</sub>
Differential Reference	Clock Input	Pins (XA/XB)		•		
Input Voltage Swing	XA/XB <sub>VPP</sub>	RATE[1:0] = LM, ML, MH, or HM	0.5	_	1.2	V <sub>PP</sub> , each.
CKINn Input Pins						
Input Frequency	CKN <sub>F</sub>		0.002	_	710	MHz
Input Duty Cycle (Minimum Pulse Width)	CKN <sub>DC</sub>	Whichever is smaller (i.e., the 40% / 60% limitation applies only to high frequency clocks)	40	_	60	%
			2	_	_	ns
Input Capacitance	CKN <sub>CIN</sub>		_	_	3	pF
Input Rise/Fall Time	CKN <sub>TRF</sub>	20–80% See Figure 2	_	_	11	ns
CKOUTn Output Pins		· · · · · · · · · · · · · · · · · · ·				
(See ordering section for		, , , , , , , , , , , , , , , , , , ,		1	T	1
Output Frequency (Output not config-	CKO <sub>F</sub>	N1 ≥ 6	0.002	_	945	MHz
ured for CMOS or Disabled)		N1 = 5	970	_	1134	MHz
,		N1 = 4	1.213	_	1.4	GHz
Maximum Output Frequency in CMOS Format	CKO <sub>F</sub>		_	_	212.5	MHz
Output Rise/Fall (20–80 %) @ 622.08 MHz output	CKO <sub>TRF</sub>	Output not configured for CMOS or Disabled See Figure 2	_	230	350	ps
Output Rise/Fall (20–80%) @ 212.5 MHz output	CKO <sub>TRF</sub>	CMOS Output $V_{DD} = 1.71$ $C_{LOAD} = 5 \text{ pF}$	_	_	8	ns

### **Table 4. AC Specifications (Continued)**

 $(V_{DD} = 1.8 \pm 5\%, 2.5 \pm 10\%, \text{ or } 3.3 \text{ V } \pm 10\%, T_A = -40 \text{ to } 85 \text{ °C})$ 

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Output Rise/Fall (20–80%) @ 212.5 MHz output	CKO <sub>TRF</sub>	CMOS Output — — — $V_{DD} = 2.97$ $C_{LOAD} = 5 pF$		_	2	ns
Output Duty Cycle Uncertainty @ 622.08 MHz	CKO <sub>DC</sub>	100 Ω Load Line-to-Line Measured at 50% Point (Not for CMOS)	_	_	+/-40	ps
LVCMOS Input Pins						
Minimum Reset Pulse Width	t <sub>RSTMN</sub>		1			μs
Reset to Microprocessor Access Ready	t <sub>READY</sub>				10	ms
Input Capacitance	C <sub>in</sub>		_	_	3	pF
LVCMOS Output Pins	1	,			1	
Rise/Fall Times	t <sub>RF</sub>	C <sub>LOAD</sub> = 20pf See Figure 2	_	25	_	ns
LOSn Trigger Window	LOS <sub>TRIG</sub>	From last CKINn ↑ to ↓ Internal detection of LOSn N3 ≠ 1	t CKINn ↑ to ↓ — — tection of LOSn		4.5 x N3	T <sub>CKIN</sub>
Time to Clear LOL after LOS Cleared	t <sub>CLRLOL</sub>	↓LOS to ↓LOL Fold = Fnew Stable Xa/XB reference	_	10	_	ms
Device Skew						
Output Clock Skew	t <sub>SKEW</sub>	↑ of CKOUTn to ↑ of CKOUT_m, CKOUTn and CKOUT_m at same frequency and signal format  PHASEOFFSET = 0  CKOUT ALWAYS ON = 1  SQ ICAL = 1	_	_	100	ps
Phase Change due to Temperature Variation	t <sub>TEMP</sub>	Max phase changes from -40 to +85 °C	_	300	500	ps

Table 4. AC Specifications (Continued) (V<sub>DD</sub> = 1.8  $\pm$  5%, 2.5  $\pm$ 10%, or 3.3 V  $\pm$ 10%, T<sub>A</sub> = -40 to 85 °C)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit			
PLL Performance						•			
(fin=fout = 622.08 MHz	(fin=fout = 622.08 MHz; BW=120 Hz; LVPECL)								
Lock Time	t <sub>LOCKMP</sub>	Start of ICAL to ↓ of LOL	_	35	1200	ms			
Output Clock Phase Change	t <sub>P_STEP</sub>	After clock switch f3 ≥ 128 kHz	1	200	_	ps			
Closed Loop Jitter Peaking	J <sub>PK</sub>			0.05	0.1	dB			
Jitter Tolerance	J <sub>TOL</sub>	Jitter Frequency ≥ Loop Bandwidth	5000/BW	_	_	ns pk-pk			
Phase Noise fout = 622.08 MHz		1 kHz Offset	_	-106	-87	dBc/Hz			
10dt = 022.00 Wii 12	01/0	10 kHz Offset	_	-121	-100	dBc/Hz			
	CKO <sub>PN</sub>	100 kHz Offset	_	-132	-104	dBc/Hz			
		1 MHz Offset	_	-132	-119	dBc/Hz			
Subharmonic Noise	SP <sub>SUBH</sub>	Phase Noise @ 100 kHz Offset	_	-88	-76	dBc			
Spurious Noise	SP <sub>SPUR</sub>	Max spur @ n x F3 (n ≥ 1, n x F3 < 100 MHz)	_	-93	-70	dBc			

**Table 5. Jitter Generation** 

Parameter	Symbol	Test Condition	on <sup>*</sup>	Min	Тур	Max	GR-253-	Unit
		Measurement Filter	DSPLL BW <sup>2</sup>				Specification	
Jitter Gen OC-192	JGEN	0.02-80 MHz	120 Hz	1	4.2	6.2	30	ps <sub>PP</sub>
00 102					.27	.42	N/A	ps <sub>rms</sub>
		4–80 MHz	120 Hz	_	3.7	6.4	10	ps <sub>PP</sub>
				_	.14	0.31	N/A	ps <sub>rms</sub>
		0.05–80 MHz	120 Hz		4.4	6.9	10	ps <sub>PP</sub>
				_	.26	0.41	1.0	ps <sub>rms</sub>
Jitter Gen OC-48	JGEN	0.12–20 MHz	120 Hz	_	3.5	5.4	40.2	ps <sub>PP</sub>
				_	.27	0.41	4.02	ps <sub>rms</sub>

\*Note: Test conditions:

1.fIN = fOUT = 622.08 MHz

2.Clock input: LVPECL

3.Clock output: LVPECL4.PLL bandwidth: 120 Hz

5.114.285 MHz 3rd OT crystal used as XA/XB input

 $6.V_{DD} = 2.5 V$ 

7.T<sub>A</sub> = 85 °C

### **Table 6. Thermal Characteristics**

(V<sub>DD</sub> = 1.8 ±5%, 2.5 ±10%, or 3.3 V ±10%,  $T_A$  = –40 to 85 °C)

Parameter	Symbol	Test Condition	Value	Unit
Thermal Resistance Junction to Ambient	$\theta_{\sf JA}$	Still Air	32	C°/W
Thermal Resistance Junction to Case	θЈС	Still Air	14	C°/W

**Table 7. Absolute Limits** 

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
DC Supply Voltage	V <sub>DD</sub>		-0.5	_	3.8	V
LVCMOS Input Voltage	V <sub>DIG</sub>		-0.3		V <sub>DD</sub> +0.3	V
CKINn Voltage Level Limits	CKN <sub>VIN</sub>		0	_	V <sub>DD</sub>	V
XA/XB Voltage Level Limits	XA <sub>VIN</sub>		0	_	1.2	V
Operating Junction Temperature	T <sub>JCT</sub>		<b>-</b> 55	_	150	°C
Storage Temperature Range	T <sub>STG</sub>		<b>-</b> 55	_	150	۰C
ESD HBM Tolerance (100 pF, 1.5 k $\Omega$ ); All pins except CKIN+/CKIN–			2	_	_	kV
ESD MM Tolerance; All pins except CKIN+/CKIN-			150	_	_	V
ESD HBM Tolerance (100 pF, 1.5 kΩ); CKIN+/CKIN-			750	_	_	V
ESD MM Tolerance; CKIN+/CKIN-			100	_	_	V
Latch-up Tolerance				JESD78	Compliant	

### 2. Typical Phase Noise Performance

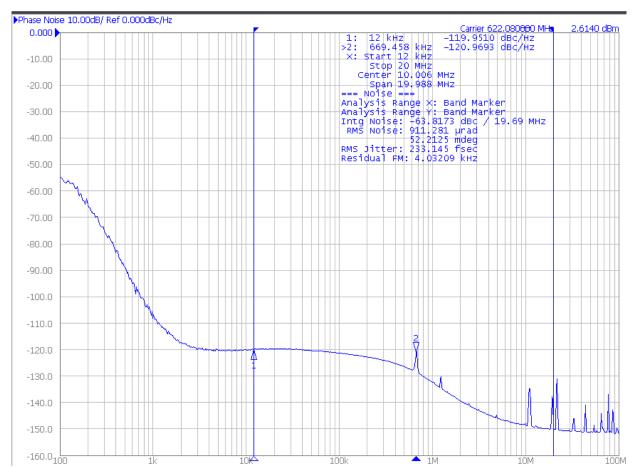


Figure 3. Typical Phase Noise Plot

Jitter Band	Jitter, RMS
SONET_OC48, 12 kHz to 20 MHz	249 fs
SONET_OC192_A, 20 kHz to 80 MHz	274 fs
SONET_OC192_B, 4 MHz to 80 MHz	166 fs
SONET_OC192_C, 50 kHz to 80 MHz	267 fs
Brick Wall_800 Hz to 80 MHz	274 fs

\*Note: Jitter integration bands include low-pass (-20 dB/Dec) and hi-pass (-60 dB/Dec) roll-offs per Telecordia GR-253-CORE.

### 3. Typical Application Circuit

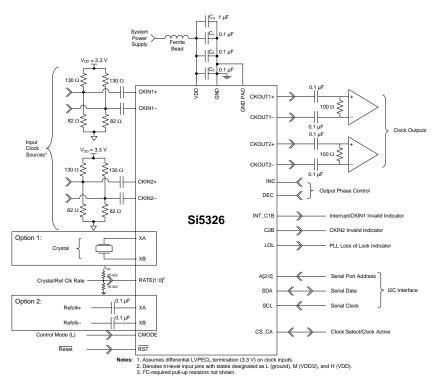


Figure 4. Si5326 Typical Application Circuit (I<sup>2</sup>C Control Mode)

Note: For an example schematic and layout, refer to the Si5325/26-EVB User's Guide.

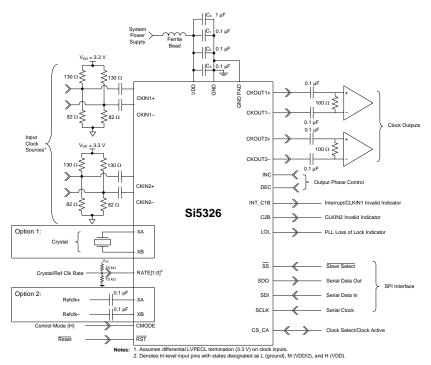


Figure 5. Si5326 Typical Application Circuit (SPI Control Mode)

Note: For an example schematic and layout, refer to the Si5325/26-EVB User's Guide.

### 4. Functional Description

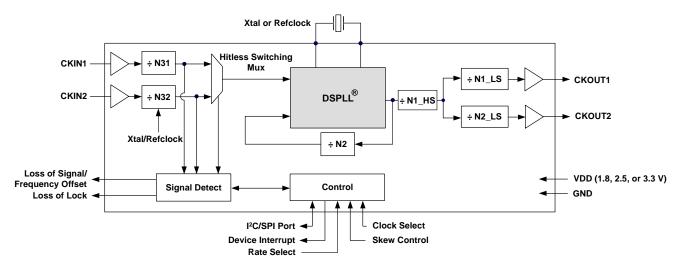


Figure 6. Functional Block Diagram

The Si5326 is a jitter-attenuating precision clock multiplier for applications requiring sub 1 ps jitter performance. The Si5326 accepts two input clocks ranging from 2 kHz to 710 MHz and generates two output clocks ranging from 2 kHz to 945 MHz and select frequencies to 1.4 GHz. The Si5326 can also use its crystal oscillator as a clock source for frequency synthesis. The device provides virtually any frequency translation combination across this operating range. Independent dividers are available for each input clock and output clock, so the Si5326 can accept input clocks at different frequencies and it can generate output clocks at different frequencies. The Si5326 input clock frequency and clock multiplication ratio programmable through an I<sup>2</sup>C or SPI interface.

Skyworks Solutions offers a PC-based software utility, DSPLLsim, that can be used to determine the optimum PLL divider settings for a given input frequency/clock multiplication ratio combination that minimizes phase noise and power consumption.

This utility can be downloaded from https://www.skyworksinc.com/en/Products/Timing-Jitter-Attenuators.

The Si5326 is based on Skyworks Solutions' 3rd-generation DSPLL® technology, which provides any frequency synthesis and jitter attenuation in a highly integrated PLL solution that eliminates the need for external VCXO and loop filter components. The Si5326 PLL loop bandwidth is digitally programmable and supports a range from 60 Hz to 8.4 kHz. The DSPLLsim software utility can be used to calculate valid loop bandwidth settings for a given input clock frequency/clock multiplication ratio.

The Si5326 supports hitless switching between the two synchronous input clocks in compliance with GR-253-CORE that greatly minimizes the propagation of phase transients to the clock outputs during an input clock transition (maximum 200 ps phase change). Manual and automatic revertive and non-revertive input clock switching options are available.

The Si5326 monitors both input clocks for loss-of-signal (LOS) and provides a LOS alarm (INT\_C1B and C2B) when it detects missing pulses on either input clock. The device monitors the lock status of the PLL. The lock detect algorithm works by continuously monitoring the phase of the input clock in relation to the phase of the feedback clock.

The Si5326 also monitors frequency offset alarms (FOS), which indicate if an input clock is within a specified frequency band relative to the frequency of a reference clock. Both Stratum 3/3E and SONET Minimum Clock (SMC) FOS thresholds supported. The Si5326 provides a digital hold capability that allows the device to continue generation of a stable output clock when the selected input reference is lost. During digital hold, the DSPLL generates an output frequency based on a historical average frequency that existed for a fixed amount of time before the error event occurred, eliminating the effects of phase and frequency transients that may occur immediately preceding digital

The Si5326 has two differential clock outputs. The electrical format of each clock output is independently programmable to support LVPECL, LVDS, CML, or CMOS loads. If not required, the second clock output can be powered down to minimize power consumption. The phase difference between the selected input clock and the output clocks is adjustable in 200 ps increments for system skew control using the CLAT[7:0] register. Fine phase adjustment is available and is set using the FLAT register bits. The nominal range and resolution of the FLAT[14:0] skew adjustment word are: ±110 ps and 3 ps, respectively. In addition, the phase of one output clock may be adjusted in relation to the phase of the other output clock. The resolution varies from 800 ps to 2.2 ns depending on the PLL divider settings. See Table 8 for instructions on ensuring output-to-output alignment. The input to output skew is not specified. The DSPLLsim software utility determines the phase offset resolution for a given input clock/clock multiplication ratio combination. For system-level debugging, a bypass mode is available which drives the output clock directly from the input clock, bypassing the internal DSPLL. The device is powered by a single 1.8, 2.5, or 3.3 V supply.

### 4.1. External Reference

An external, high quality clock or a low-cost 114.285 MHz 3rd overtone crystal is used as part of a fixed-frequency oscillator within the DSPLL. This external reference is required for the device to perform jitter attenuation. Skyworks Solutions recommends using a high quality crystal. Specific recommendations may be found in the Family Reference Manual.

In digital hold, the DSPLL remains locked and tracks the external reference. Note that crystals can have temperature sensitivities.

### 4.2. Further Documentation

Consult the Skyworks Solutions Si53xx Any Frequency Precision Clock Family Reference Manual (FRM) for detailed information about the Si5326 functions. Additional design support is available from Skyworks Solutions through your distributor.

Skyworks Solutions has developed a PC-based software utility called DSPLLsim to simplify device configuration, including frequency planning and loop bandwidth selection.

The FRM and this utility can be downloaded from https://www.skyworksinc.com/en/Products/Timing-Jitter-Attenuators.

CKOUT ALWAYS ON	SQ ICAL	Results
0	0	CKOUT OFF until after the first ICAL
0	U	CROOT OFF until after the first ICAL
0	1	CKOUT OFF until after the first successful ICAL (i.e., when LOL is low)
1	0	CKOUT always ON, including during an ICAL
1	1	CKOUT always ON, including during an ICAL. Use these settings to preserve output-to-output skew

Table 8. CKOUT ALWAYS ON and SQ ICAL Truth Table

### 5. Register Map

All register bits that are not defined in this map should always be written with the specified Reset Values. The writing to these bits of values other than the specified Reset Values may result in undefined device behavior. Registers not listed, such as Register 64, should never be written to.

Register	D7	D6	D5	D4	D3	D2	D1	D0
0		FREE_RUN	CKOUT_ ALWAYS_ ON				BYPASS_ REG	
1					CK_PR	IOR2[1:0]	CK_PR	IOR[1:0]
2		BWSEL_	REG[3:0]					
3	CKSEL_	REG[1:0]	DHOLD	SQ_ICAL				
4	AUTOSEL	_REG[1:0]			1	HST_DEL[4:0]		ı
5	ICMO	S[1:0]						
6		SLEEP	SF	OUT2_REG[	2:0]	SF	OUT1_REG[2	2:0]
7						F	OSREFSEL[2:	0]
8	HLOG	_2[1:0]	HLOG	_1[1:0]				
9		ŀ	HIST_AVG[4:0	]				
10					DSBL2_ REG	DSBL1_ REG		
11							PD_CK2	PD_CK1
16				CLA	T[7:0]			
17	FLAT_VALID				FLAT[14:8]			
18				FLA	T[7:0]			
19	FOS_EN	FOS_T	HR[1:0]	VALTI	ME[1:0]	1E[1:0] LOCK[T2:0]		
20					CK2_ BAD_ PIN	CK1_ BAD_ PIN	LOL_PIN	INT_PIN
21	INCDEC_ PIN						CK1_ACT- V_PIN	CKSEL_PIN
22					CK_ACTV_ POL	CK_BAD_ POL	LOL_POL	INT_POL
23						LOS2_MSK	LOS1_MSK	LOSX_MSK
24						FOS2_MSK	FOS1_MSK	LOL_MSK
25		N1_HS[2:0]						
31						NC1_LS	S[19:16]	
32				NC1_	LS[15:8]			

Register	D7	D6	D5	D4	D3	D2	D1	D0		
33		-		NC1_	LS[7:0]	I	I			
34					NC2_LS[19:16]					
35		NC2_LS[15:8]								
36		NC2_LS[7:0]								
40		N2_HS[2:0]				N2_LS	[19:16]			
41				N2_L	S[15:8]					
42				N2_L	.S[7:0]					
43							N31[18:16]			
44				N31	[15:8]					
45				N31	[7:0]					
46							N32[18:16]			
47				N32	[15:8]	1				
48		N32[7:0]								
55			C	LKIN2RATE[2:	2:0] CLKIN1RATE[2:0]					
128							CK2_ACT- V_REG	CK1_ACT- V_REG		
129						LOS2_INT	LOS1_INT	LOSX_INT		
130	CLATPROG- RESS	DIGHOLD- VALID				FOS2_INT	FOS1_INT	LOL_INT		
131						LOS2_FLG	LOS1_FLG	LOSX_FLG		
132					FOS2_FLG	FOS1_FLG	LOL_FLG			
134				PARTNUN	/_RO[11:4]					
135		PARTNUN	/_RO[3:0]			REVID_	RO[3:0]			
136	RST_REG	ICAL					GRADE	_RO[1:0]		
138							LOS2_EN [1:1]	LOS1_EN [1:1]		
139			LOS2_EN [0:0]	LOS1_EN [0:0]			FOS2_EN	FOS1_EN		
142				INDEPENDE	NTSKEW1[7:0]	1	1	1		
143				INDEPENDE	NTSKEW2[7:0]					

### 6. Register Descriptions

### Register 0.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name		FREE_ RUN	CKOUT_ ALWAYS_ ON				BYPASS_ REG	
Туре	R	R/W	R/W	R	R	R	R/W	R

Bit	Name	Function
7	Reserved	Reserved.
6	FREE_RUN	Free Run. Internal to the device, route XA/XB to CKIN2. This allows the device to lock to its XA-XB reference.  0: Disable 1: Enable
5	CKOUT_ ALWAYS_ON	CKOUT Always On.  This will bypass the SQ_ICAL function. Output will be available even if SQ_ICAL is on and ICAL is not complete or successful. See Table 8 on page 19.  0: Squelch output until part is calibrated (ICAL).  1: Provide an output. Note: The frequency may be significantly off and variable until the part is calibrated.
4:2	Reserved	Reserved.
1	BYPASS_ REG	Bypass Register.  This bit enables or disables the PLL bypass mode. Use only when the device is in digital hold or before the first ICAL.  0: Normal operation  1: Bypass mode. Selected input clock is connected to CKOUT buffers, bypassing the PLL. Bypass mode does not support CMOS clock outputs.
0	Reserved	Reserved.

### Register 1.

Bit	D7	D6	D5	D4	D3	D2	D1	D0	
Name		Rese	erved		CK_PRIC	DR2 [1:0]	CK_PRIOR1 [1:0]		
Туре		R				W	R/	W	

Reset value = 1110 0100

Bit	Name	Function
7:4	Reserved	Reserved.
3:2	CK_PRIOR2 [1:0]	CK_PRIOR 2.  Selects which of the input clocks will be 2nd priority in the autoselection state machine.  00: CKIN1 is 2nd priority.  01: CKIN2 is 2nd priority.  10: Reserved  11: Reserved
1:0	CK_PRIOR1 [1:0]	CK_PRIOR 1.  Selects which of the input clocks will be 1st priority in the autoselection state machine.  00: CKIN1 is 1st priority.  01: CKIN2 is 1st priority.  10: Reserved  11: Reserved

### Register 2.

Bit	D7	D6	D5	D4	D3	D2	D1	D0	
Name		BWSEL_I	REG [3:0]		Reserved				
Туре		R/	W		R				

Bit	Name	Function
7:4	BWSEL_REG	BWSEL_REG.
	[3:0]	Selects nominal f3dB bandwidth for PLL. See DSPLLsim for settings. After BWSEL_REG is written with a new value, an ICAL is required for the change to take effect.
3:0	Reserved	Reserved.

### Register 3.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	CKSEL_I	CKSEL_REG [1:0]		SQ_ICAL		Rese	erved	
Туре	R/W		R/W	R/W	R			

Bit	Name	Function
7:6	CKSEL_REG [1:0]	CKSEL_REG.  If the device is operating in register-based manual clock selection mode  (AUTOSEL_REG = 00), and CKSEL_PIN = 0, then these bits select which input clock will be the active input clock. If CKSEL_PIN = 1 and AUTOSEL_REG = 00, the CS_CA input pin continues to control clock selection and CKSEL_REG is of no consequence.  00: CKIN_1 selected. 01: CKIN_2 selected. 10: Reserved
5	DHOLD	DHOLD. Forces the part into digital hold. This bit overrides all other manual and automatic clock selection controls. 0: Normal operation. 1: Force digital hold mode. Overrides all other settings and ignores the quality of all of the input clocks.
4	SQ_ICAL	SQ_ICAL.  This bit determines if the output clocks will remain enabled or be squelched (disabled) during an internal calibration. See Table 8 on page 19.  0: Output clocks enabled during ICAL.  1: Output clocks disabled during ICAL.
3:0	Reserved	Reserved.

### Register 4.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	AUTOSEL_REG [1:0]		Reserved		F	IIST_DEL [4:0	0]	
Туре	R/	W	R			R/W		

Reset value = 0001 0010

Bit	Name	Function
7:6	AUTOSEL_ REG [1:0]	AUTOSEL_REG [1:0].  Selects method of input clock selection to be used.  00: Manual (either register or pin controlled, see CKSEL_PIN)  01: Automatic Non-Revertive  10: Automatic Revertive  11: Reserved  See the Si53xx Family Reference Manual for a detailed description.
5	Reserved	Reserved.
5	Reserved	
4:0	HIST_DEL [4:0]	HIST_DEL [4:0].  Selects amount of delay to be used in generating the history information used for Digital Hold.  See the Si53xx Family Reference Manual for a detailed description.

### Register 5.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	ICMOS [1:0]				Rese	erved		
Туре	R/W				F	3		

Reset value = 1110 1101

Bit	Name	Function
7:6	ICMOS [1:0]	ICMOS [1:0].  When the output buffer is set to CMOS mode, these bits determine the output buffer drive strength. The first number below refers to 3.3 V operation; the second to 1.8 V operation. These values assume CKOUT+ is tied to CKOUT  00: 8mA/2mA 01: 16mA/4mA 10: 24mA/6mA 11: 32mA/8mA
5:0	Reserved	Reserved.

### Register 6.

Bit	D7	D6	D5	D4	D3	D2	D1	D0		
Name	Reserved	SLEEP	SFO	SFOUT2_REG [2:0]			SFOUT1_REG [2:0]			
Туре	R	R/W		R/W			R/W			

Bit	Name	Function
7	Reserved	Reserved.
6	SLEEP	SLEEP.  In sleep mode, all clock outputs are disabled and the maximum amount of internal circuitry is powered down to reduce power dissipation and noise generation. This bit overrides the SFOUTn_REG[2:0] output signal format settings.  0: Normal operation 1: Sleep mode
5:3	SFOUT2_ REG [2:0]	SFOUT2_REG [2:0].  Controls output signal format and disable for CKOUT2 output buffer.  000: Reserved  001: Disable  010: CMOS (Bypass mode not supported)  011: Low swing LVDS  100: Reserved  101: LVPECL  110: CML  111: LVDS  Note: LVPECL requires a nominal V <sub>DD</sub> ≥ 2.5 V.
2:0	SFOUT1_ REG [2:0]	SFOUT1_REG [2:0].  Controls output signal format and disable for CKOUT1 output buffer.  000: Reserved  001: Disable  010: CMOS (Bypass mode not supported)  011: Low swing LVDS  100: Reserved  101: LVPECL  110: CML  111: LVDS  Note: LVPECL requires a nominal V <sub>DD</sub> ≥ 2.5 V.

### Register 7.

Bit	D7	D6	D5	D4	D3	D2	D1	D0	
Name		Reserved					FOSREFSEL [2:0]		
Туре			R			R/W			

Bit	Name	Function
7:3	Reserved.	Reserved.
2:0	FOSREFSEL [2:0]	FOSREFSEL [2:0]. Selects which input clock is used as the reference frequency for frequency offset (FOS) alarms.  000: XA/XB (External reference)  001: CKIN1  010: CKIN2  011: Reserved  100: Reserved  111: Reserved

### Register 8.

Bit	D7	D6	D5	D4	D3	D2	D1	D0		
Name	HLOG	_2[1:0]	HLOG_1[1:0]		Reserved					
Туре	R/	R/W		R/W		R				

Reset value = 0000 0000

Bit	Name	Function
7:6	HLOG_2 [1:0]	HLOG_2 [1:0].  00: Normal operation  01: Holds CKOUT2 output at static logic 0. Entrance and exit from this state will occur without glitches or runt pulses.  10: Holds CKOUT2 output at static logic 1. Entrance and exit from this state will occur without glitches or runt pulses.  11: Reserved
5:4		HLOG_1 [1:0].  00: Normal operation  01: Holds CKOUT1 output at static logic 0. Entrance and exit from this state will occur without glitches or runt pulses.  10: Holds CKOUT1 output at static logic 1. Entrance and exit from this state will occur without glitches or runt pulses.  11: Reserved
3:0	Reserved	Reserved.

### Register 9.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name		Н	IST_AVG [4:0		Reserved			
Туре		R/W					R	R

Reset value = 1100 0000

Bit	Name	Function
7:3	HIST_AVG	HIST_AVG [4:0].
	[4:0]	Selects amount of averaging time to be used in generating the history information for Digital Hold. See the Si53xx Family Reference Manual for a detailed description
2:0	Reserved	Reserved.

### Register 10.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved			DSBL2_ REG	DSBL1_ REG	Reserved	Reserved	
Туре		R			R/W	R/W	R	R

Bit	Name	Function
7:4	Reserved	Reserved.
3	DSBL2_REG	DSBL2_REG. This bit controls the powerdown of the CKOUT2 output buffer. If disable mode is selected, the N2_LS output divider is also powered down.  0: CKOUT2 enabled  1: CKOUT2 disabled
2	DSBL1_REG	DSBL1_REG. This bit controls the powerdown of the CKOUT1 output buffer. If disable mode is selected, the N1_LS output divider is also powered down.  0: CKOUT1 enabled  1: CKOUT1 disabled
1:0	Reserved	Reserved.

### Register 11.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name		Reserved						PD_CK1
Туре		R						R/W

Reset value = 0100 0000

Bit	Name	Function
7:2	Reserved	Reserved.
1	PD_CK2	PD_CK2.
		This bit controls the powerdown of the CKIN2 input buffer.  0: CKIN2 enabled  1: CKIN2 disabled
0	PD_CK1	PD_CK1. This bit controls the powerdown of the CKIN1 input buffer. 0: CKIN1 enabled 1: CKIN1 disabled

### Register 16.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name		CLAT [7:0]						
Туре		R/W						

Bit	Name	Function
7:0	CLAT [7:0]	CLAT [7:0].  With INCDEC_PIN = 0, this register sets the phase delay for CKOUTn in units of
		1/Fosc. This can take as long as 20 seconds. 01111111 = 127/Fosc (2s compliment) 00000000 = 0 10000000 = -128/Fosc (2s compliment) If NI_HS[2:0] = 000, increasing CLAT does not work.

### Register 17.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	FLAT_ VALID				FLAT [14:8]			
Туре	R/W				R/W			

Reset value = 1000 0000

Bit	Name	Function
7	FLAT_VALID	FLAT_VALID.
		Before writing a new FLAT[14:0] value, this bit must be set to zero, which causes the existing FLAT[14:0] value to be held internally for use while the new value is being written. Once the new FLAT[14:0] value is completely written, set FLAT_VALID = 1 to enable its use.  0: Memorize existing FLAT[14:0] value and ignore intermediate register values during write of new FLAT[14:0] value.  1: Use FLAT[14:0] value directly from registers.
6:0	FLAT [14:8]	FLAT [14:8].
		Fine resolution control for overall device skew from input clocks to output clocks. Positive values increase the skew. See DSPLL <i>sim</i> for details. FLAT [14:0] is a 2's complement number.

### Register 18.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name		FLAT [7:0]						
Туре		R/W						

Bit	Name	Function
7:0	FLAT [7:0]	FLAT [7:0].  Fine resolution control for overall device skew from input clocks to output clocks. Positive values increase the skew. See DSPLLsim for details.
		FLAT [14:0] is a 2's complement number.

### Register 19.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	FOS_EN	FOS_THR [1:0]		VALTIME [1:0]		LOCKT [2:0]		
Туре	R/W	R/W		R/W		R/W		

Bit	Name	Function
7	FOS_EN	FOS_EN.
		Frequency Offset Enable globally disables FOS. See the individual FOS enables (FOSX_EN, register 139).  0: FOS disable
		1: FOS enabled by FOSx_EN
6:5	FOS_THR	FOS_THR [1:0].
	[1:0]	Frequency Offset at which FOS is declared (relative to the selected FOS reference): 00: ± 11 to 12 ppm (Stratum 3/3E compliant, with a Stratum 3/3E used for REFCLK 01: ± 48 to 49 ppm (SMC) 10: ± 30 ppm (SONET Minimum Clock (SMC), with a Stratum 3/3E used for REFCLK.
		11: ± 200 ppm
4:3	VALTIME [1:0]	VALTIME [1:0].
		Sets amount of time for input clock to be valid before the associated alarm is removed.
		00: 2 ms
		01: 100 ms
		10: 200 ms
		11: 13 seconds
2:0	LOCKT [2:0]	LOCKT [2:0].
		Sets retrigger interval for one shot monitoring phase detector output. One shot is triggered by phase slip in DSPLL. Refer to the Si53xx Family Reference Manual for more details.
		000: 106 ms
		001: 53 ms
		010: 26.5 ms
		011: 13.3 ms
		100: 6.6 ms 101: 3.3 ms
		1101: 3.3 ms
		111: .833 ms
		111000 mg

### Register 20.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved			CK2_BAD_ PIN	CK1_BAD_ PIN	LOL_PIN	INT_PIN	
Туре	R			R/W	R/W	R/W	R/W	

Reset value = 0011 1110

Bit	Name	Function
7:4	Reserved	Reserved.
3	CK2_BAD_ PIN	CK2_BAD_PIN.  The CK2_BAD status can be reflected on the C2B output pin.  0: C2B output pin tristated  1: C2B status reflected to output pin
2	CK1_BAD_ PIN	CK1_BAD_PIN.  Either LOS1 or INT (see INT_PIN) status can be reflected on the INT_C1B output pin.  0: INT_C1B output pin tristated  1: LOS1 or INT (see INT_PIN) status reflected to output pin
1	LOL_PIN	LOL_PIN. The LOL_INT status bit can be reflected on the LOL output pin. 0: LOL output pin tristated 1: LOL_INT status reflected to output pin
0	INT_PIN	INT_PIN.  Reflects the interrupt status on the INT_C1B output pin.  0: Interrupt status not displayed on INT_C1B output pin. Instead, the INT_C1B pin indicates when CKIN1 is bad. If CK1_BAD_PIN = 0, INT_C1B output pin is tristated.  1: Interrupt status reflected to output pin.

### Register 21.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	INCDEC_ PIN			CK1_ACT- V_PIN	CKSEL_ PIN			
Туре	R/W	Force 1	R	R	R	R	R/W	R/W

Reset value = 1111 1111

Bit	Name	Function
7	INCDEC_PIN	INCDEC_PIN.  Determines how coarse skew adjustments can be made. The adjustments can be made via hardware using the INC/DEC pins or via software using the CLAT register.  0: INC and DEC inputs ignored; use CLAT register to adjust skew.  1: INC and DEC inputs control output phase increment/decrement.
6:2	Reserved	Reserved.
1	CK1_ACTV_ PIN	CK1_ACTV_PIN.  The CK1_ACTV_REG status bit can be reflected to the CS_CA output pin using the CK1_ACTV_PIN enable function. CK1_ACTV_PIN is of consequence only when pin controlled clock selection is being used. (See CKSEL_PIN)  0: CS_CA output pin tristated.  1: Clock Active status reflected to output pin.
0	CKSEL_PIN	CKSEL_PIN.  If manual clock selection is being used, clock selection can be controlled via the CKSEL_REG[1:0] register bits or the CS_CA input pin. This bit is only active when AUTOSEL_REG = Manual.  0: CS_CA pin is ignored. CKSEL_REG[1:0] register bits control clock selection.  1: CS_CA input pin controls clock selection.

### Register 22.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved			CK_ACT- V_POL	CK_BAD_ POL	LOL_POL	INT_POL	
Туре	R			R/W	R/W	R/W	R/W	

Reset value = 1101 1111

Bit	Name	Function
7:4	Reserved	Reserved.
3	CK_ACTV_ POL	CK_ACTV_POL.  Sets the active polarity for the CS_CA signals when reflected on an output pin.  0: Active low  1: Active high
2	CK_BAD_ POL	CK_BAD_POL.  Sets the active polarity for the INT_C1B and C2B signals when reflected on output pins.  0: Active low  1: Active high
1	LOL_POL	LOL_POL. Sets the active polarity for the LOL status when reflected on an output pin. 0: Active low 1: Active high
0	INT_POL	INT_POL.  Sets the active polarity for the interrupt status when reflected on the INT_C1B output pin.  0: Active low  1: Active high

### Register 23.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name			Reserved	LOS2_ MSK	LOS1_ MSK	LOSX_ MSK		
Туре		R					R/W	R/W

Bit	Name	Function
7:3	Reserved	Reserved.
2	LOS2_MSK	LOS2_MSK.
		Determines if a LOS on CKIN2 (LOS2_FLG) is used in the generation of an interrupt.  Writes to this register do not change the value held in the LOS2_FLG register.  0: LOS2 alarm triggers active interrupt on INT_C1B output (if INT_PIN=1).  1: LOS2_FLG ignored in generating interrupt output.
1	LOS1_MSK	LOS1_MSK.
		Determines if a LOS on CKIN1 (LOS1_FLG) is used in the generation of an interrupt. Writes to this register do not change the value held in the LOS1_FLG register. 0: LOS1 alarm triggers active interrupt on INT_C1B output (if INT_PIN=1). 1: LOS1_FLG ignored in generating interrupt output.
0	LOSX_MSK	LOSX_MSK.
		Determines if a LOS on XA/XB(LOSX_FLG) is used in the generation of an interrupt.  Writes to this register do not change the value held in the LOSX_FLG register.  0: LOSX alarm triggers active interrupt on INT_C1B output (if INT_PIN=1).  1: LOSX_FLG ignored in generating interrupt output.

# Register 24.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name			Reserved	FOS2_ MSK	FOS1_ MSK	LOL_MSK		
Туре			R			R/W	R/W	R/W

Reset value = 0011 1111

Bit	Name	Function
7:3	Reserved	Reserved.
2	FOS2_MSK	FOS2_MSK.
		Determines if the FOS2_FLG is used in the generation of an interrupt. Writes to this register do not change the value held in the FOS2_FLG register.
		0: FOS2 alarm triggers active interrupt on INT_C1B output (if INT_PIN=1).
		1: FOS2_FLG ignored in generating interrupt output.
1	FOS1_MSK	FOS1_MSK.
		Determines if the FOS1_FLG is used in the generation of an interrupt. Writes to this register do not change the value held in the FOS1_FLG register.
		0: FOS1 alarm triggers active interrupt on INT_C1B output (if INT_PIN=1).
		1: FOS1_FLG ignored in generating interrupt output.
0	LOL_MSK	LOL_MSK.
		Determines if the LOL_FLG is used in the generation of an interrupt. Writes to this register do not change the value held in the LOL_FLG register.  0: LOL alarm triggers active interrupt on INT_C1B output (if INT_PIN=1).  1: LOL_FLG ignored in generating interrupt output.

### Register 25.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name		N1_HS [2:0]		Reserved				
Туре	R/W					R		

Reset value = 0010 0000

Bit	Name	Function
7:5	N1_HS [2:0]	N1_HS [2:0].
		Sets value for N1 high speed divider which drives NCn_LS (n = 1 to 2) low-speed divider. 000: N1= 4 Note: Changing the coarse skew via the INC pin or CLAT register is disabled for this value. 001: N1= 5 010: N1= 6 011: N1= 7 100: N1= 8 101: N1= 9 110: N1= 10 111: N1= 11
4:0	Reserved	Reserved.

### Register 31.

Bit	D7	D6	D5	D4	D3	D2	D1	D0	
Name		Rese	erved		NC1_LS [19:16]				
Туре		F	₹			R	/W		

Bit	Name	Function
7:4	Reserved	Reserved.
3:0	NC1_LS [19:16]	NC1_LS [19:16].  Sets value for NC1 low-speed divider, which drives CKOUT1 output. Must be 0 or odd.  00000000000000000000000000000000000

# Register 32.

Bit	D7	D6	D5	D4	D3	D2	D1	D0	
Name		NC1_LS [15:8]							
Туре				R/	W				

Reset value = 0000 0000

Bit	Name	Function
7:0	NC1_LS [15:8]	NC1_LS [15:8].  Sets value for NC1 low-speed divider, which drives CKOUT1 output. Must be 0 or odd.  00000000000000000000000000000000000

### Register 33.

Bit	D7	D6	D5	D4	D3	D2	D1	D0			
Name		NC1_LS [7:0]									
Туре				R/	R/W						

Reset value = 0011 0001

Bit	Name	Function
7:0	NC1_LS [19:0]	NC1_LS [7:0].  Sets value for N1 low-speed divider, which drives CKOUT1 output. Must be 0 or odd.  000000000000000000000 = 1  00000000000

### Register 34.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name		Rese	erved		NC2_LS [19:16]			
Туре		F	?			R/	/W	

Reset value = 0000 0000

Bit	Name	Function
7:4	Reserved	Reserved.
3:0	NC2_LS [19:16]	NC2_LS [19:16].  Sets value for NC2 low-speed divider, which drives CKOUT2 output. Must be 0 or odd. 0000000000000000000000000000000000

# Register 35.

Bit	D7	D6	D5	D4	D3	D2	D1	D0	
Name		NC2_LS [15:8]							
Туре				R/	W				

Bit	Name	Function
7:0	NC2_LS [15:8]	NC2_LS [15:8].  Sets value for NC2 low-speed divider, which drives CKOUT2 output. Must be 0 or odd.  000000000000000000000 = 1  00000000000

# Register 36.

Bit	D7	D6	D5	D4	D3	D2	D1	D0	
Name		NC2_LS [7:0]							
Туре				R/	W				

#### Reset value = 0011 0001

Bit	Name	Function
7:0	NC2_LS [7:0]	NC2_LS [7:0].
		Sets value for NC2 low-speed divider, which drives CKOUT2 output. Must be 0 or odd. 0000000000000000000000000000000000

### Register 40.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	N2_HS [2:0]			Reserved		N2_LS [19:16]		
Туре		R/W				R	/W	

Reset value = 1100 0000

Bit	Name	Function
7:5	N2_HS [2:0]	N2_HS [2:0].
		Sets value for N2 high speed divider, which drives N2LS low-speed divider.
		000: 4
		001: 5
		010: 6
		011: 7
		100: 8
		101: 9
		110: 10
		111: 11
4	Reserved	Reserved.
3:0	N2_LS [19:16]	N2_LS [19:16].
		Sets value for N2 low-speed divider, which drives phase detector.
		000000000000000001 = 2
		00000000000000011 = 4
		00000000000000101 = 6
		11111111111111111 = 2^20
		Valid divider values = [2, 4, 6,, 2^20]

# Register 41.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name		N2_LS [15:8]						
Туре				R/	W			

Reset value = 0000 0000

Bit	Name	Function
7:0	N2_LS [15:8]	N2_LS [15:8].
		Sets value for N2 low-speed divider, which drives phase detector.  0000000000000000001 = 2  000000000000000011 = 4  0000000000000000101 = 6
		 1111111111111111 = 2^20 Valid divider values = [2, 4, 6,, 2^20]

### Register 42.

Bit	D7	D6	D5	D4	D3	D2	D1	D0	
Name		N2_LS [7:0]							
Туре				R/	W				

Reset value = 1111 1001

Bit	Name	Function
7:0	N2_LS [7:0]	N2_LS [7:0].
		Sets value for N2 low-speed divider, which drives phase detector.  000000000000000001 = 2  000000000000000011 = 4  000000000000000101 = 6   11111111111111111 = 2^20  Valid divider values = [2, 4, 6,, 2^20]

### Register 43.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name			Reserved	N31 [18:16]				
Туре			R		R/W			

Reset value = 0000 0000

Bit	Name	Function
7:3	Reserved	Reserved.
2:0	N31 [18:16]	N31 [18:16].
		Sets value for input divider for CKIN1.  000000000000000000 = 1  00000000000000

# Register 44.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name		N31_[15:8]						
Туре		R/W						

Bit	Name	Function
7:0	N31_[15:8]	N31_[15:8].
		Sets value for input divider for CKIN1.  0000000000000000000 = 1  0000000000000
		111111111111111 = 2^19 Valid divider values=[1, 2, 3,, 2^19]

# Register 45.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name		N31_[7:0]						
Туре				R/	W			

Reset value = 0000 1001

Bit	Name	Function
7:0	N31_[7:0	N31_[7:0].
		Sets value for input divider for CKIN1. 00000000000000000 = 1 0000000000000000 = 2 00000000000000000 = 3
		 1111111111111111 = 2^19 Valid divider values=[1, 2, 3,, 2^19]

### Register 46.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name			Reserved	N32_[18:16]				
Туре			R		R/W			

Bit	Name	Function
7:3	Reserved	Reserved.
2:0	N32_[18:16]	N32_[18:16].
		Sets value for input divider for CKIN2.  000000000000000000 = 1  00000000000000

### Register 47.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name		N32_[15:8]						
Туре				R/	W			

Reset value = 0000 0000

Bit	Name	Function
7:0	N32_[15:8]	N32_[15:8]. Sets value for input divider for CKIN2. 0000000000000000000 = 1 000000000000000

# Register 48.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name		N32_[7:0]						
Туре		R/W						

Bit	Name	Function
7:0	N32_[7:0]	N32_[7:0]. Sets value for input divider for CKIN1.  0000000000000000000 = 1  0000000000000
		111111111111111 = 2^19 Valid divider values=[1, 2, 3,, 2^19]

# Register 55.

Bit	D7	D6	D5	D4	D3	D2	D1	D0	
Name	Reserved		CL	CLKIN2RATE_[2:0]			CLKIN1RATE[2:0]		
Туре	R		R/W			R/W			

Bit	Name	Function
7:6	Reserved	Reserved.
5:3	CLKIN2RATE [2:0]	CLKIN2RATE[2:0].  CKINn frequency selection for FOS alarm monitoring.  000: 10 - 27 MHz  001: 25 - 54 MHz  010: 50 - 105 MHz  011: 95 - 215 MHz  100: 190 - 435 MHz  101: 375 - 710 MHz  110: Reserved  111: Reserved
2:0	CLKIN1RATE [2:0]	CLKIN1RATE[2:0]. CKINn frequency selection for FOS alarm monitoring. 000: 10 - 27 MHz 001: 25 - 54 MHz 010: 50 - 105 MHz 011: 95 - 215 MHz 100: 190 - 435 MHz 101: 375 - 710 MHz 110: Reserved 111: Reserved

### Register 128.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name		Reserved						CK1_ACT- V_REG
Туре		R						R

Bit	Name	Function
7:2	Reserved	Reserved.
1	CK2_ACTV_ REG	CK2_ACTV_REG. Indicates if CKIN2 is currently the active clock for the PLL input.  0: CKIN2 is not the active input clock. Either it is not selected or LOS2_INT is 1.  1: CKIN2 is the active input clock.
0	CK1_ACTV_ REG	CK1_ACTV_REG. Indicates if CKIN1 is currently the active clock for the PLL input.  0: CKIN1 is not the active input clock. Either it is not selected or LOS1_INT is 1.  1: CKIN1 is the active input clock.

# Register 129.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name		Reserved					LOS1_INT	LOSX_INT
Туре		R					R	R

Bit	Name	Function
7:3	Reserved	Reserved.
2	LOS2_INT	LOS2_INT. Indicates the LOS status on CKIN2. 0: Normal operation.
		1: Internal loss-of-signal alarm on CKIN2 input.
1	LOS1_INT	LOS1_INT. Indicates the LOS status on CKIN1. 0: Normal operation. 1: Internal loss-of-signal alarm on CKIN1 input.
0	LOSX_INT	LOSX_INT. Indicates the LOS status of the external reference on the XA/XB pins. 0: Normal operation. 1: Internal loss-of-signal alarm on XA/XB reference clock input.

# Register 130.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	CLATPROG- RESS	DIGHOLD- VALID		Reserved		FOS2_INT	FOS1_INT	LOL_INT
Туре	R	R		R		R	R	R

Bit	Name	Function
7	CLATPROG- RESS	CLAT Progress. Indicates if the last change in the CLAT register has been processed. 0: Coarse skew adjustment not in progress. 1: Coarse skew adjustment in progress.
6	DIGHOLD- VALID	Digital Hold Valid. Indicates if the digital hold circuit has enough samples of a valid clock to meet digital hold specifications.  0: Indicates digital hold history registers have not been filled. The digital hold output frequency may not meet specifications.  1: Indicates digital hold history registers have been filled. The digital hold output frequency is valid.
5:3	Reserved	Reserved.
2	FOS2_INT	CKIN2 Frequency Offset Status.  0: Normal operation.  1: Internal frequency offset alarm on CKIN2 input.
1	FOS1_INT	CKIN1 Frequency Offset Status.  0: Normal operation.  1: Internal frequency offset alarm on CKIN1 input.
0	LOL_INT	PLL Loss of Lock Status.  0: PLL locked.  1: PLL unlocked.

# Register 131.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name			Reserved	LOS2_FLG	LOS1_FLG	LOSX_FLG		
Туре		R					R/W	R/W

Bit	Name	Function
7:3	Reserved	Reserved.
2	LOS2_FLG	CKIN2 Loss-of-Signal Flag.
		0: Normal operation. 1: Held version of LOS2_INT. Generates active output interrupt if output interrupt pin is enabled (INT_PIN = 1) and if not masked by LOS2_MSK bit. Flag cleared by writing 0 to this bit.
1	LOS1_FLG	CKIN1 Loss-of-Signal Flag.
		0: Normal operation
		1: Held version of LOS1_INT. Generates active output interrupt if output interrupt pin is enabled (INT_PIN = 1) and if not masked by LOS1_MSK bit. Flag cleared by writing 0 to this bit.
0	LOSX_FLG	External Reference (signal on pins XA/XB) Loss-of-Signal Flag.
		0: Normal operation
		1: Held version of LOSX_INT. Generates active output interrupt if output interrupt pin is enabled (INT_PIN = 1) and if not masked by LOSX_MSK bit. Flag cleared by writing 0 to this bit.

# Register 132.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved				FOS2_FLG	FOS1_FLG	LOL_FLG	Reserved
Туре	R				R/W	R/W	R/W	R

Bit	Name	Function
7:4	Reserved	Reserved.
3	FOS2_FLG	CLKIN_2 Frequency Offset Flag.
		O: Normal operation.  1: Held version of FOS2_INT. Generates active output interrupt if output interrupt pin is enabled (INT_PIN = 1) and if not masked by FOS2_MSK bit. Flag cleared by writing 0 to this bit.
2	FOS1_FLG	CLKIN_1 Frequency Offset Flag.
		0: Normal operation 1: Held version of FOS1_INT. Generates active output interrupt if output interrupt pin is enabled (INT_PIN = 1) and if not masked by FOS1_MSK bit. Flag cleared by writing 0 to this bit.
1	LOL_FLG	PLL Loss of Lock Flag.
		0: PLL locked 1: Held version of LOL_INT. Generates active output interrupt if output interrupt pin is enabled (INT_PIN = 1) and if not masked by LOL_MSK bit. Flag cleared by writing 0 to this bit.
0	Reserved	Reserved.

# Register 134.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name		PARTNUM_RO [11:4]						
Туре				F	₹			

Reset value = 0000 0001

В	it	Name	Function
7:	0		Device ID (1 of 2). 0000 0001 1010: Si5326

# Register 135.

Bit	D7	D6	D5	D4	D3	D2	D1	D0	
Name		PARTNUM	1_RO [3:0]		REVID_RO [3:0]				
Туре		F	₹			F	₹		

Reset value = 1010 0010

Bit	Name	Function
7:4	PARTNUM_ RO [11:0]	<b>Device ID (2 of 2).</b> 0000 0001 1010: Si5326
3:0	REVID_RO [3:0]	Device Revision.  0000: Revision A  0001: Revision B  0010: Revision C  Others: Reserved

### Register 136.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	RST_REG	ICAL	Reserved					
Туре	R/W	R/W		R				

Bit	Name	Function
7	RST_REG	Internal Reset (Same as Pin Reset).
		<b>Note:</b> The I <sup>2</sup> C (or SPI) port may not be accessed until 10 ms after RST_REG is asserted. 0: Normal operation.
		1: Reset of all internal logic. Outputs disabled or tristated during reset.
6	ICAL	Start an Internal Calibration Sequence.
		For proper operation, the device must go through an internal calibration sequence. ICAL is a self-clearing bit. Writing a "1" to this location initiates an ICAL. The calibration is complete once the LOL alarm goes low.  0: Normal operation.
		1: Writing a "1" initiates internal self-calibration. Upon completion of internal self-calibration, LOL will go low.
		<ol> <li>Notes:         <ol> <li>A valid stable clock (within 100 ppm) must be present to begin ICAL.</li> <li>If the input changes by more than 500 ppm, the part may do an autonomous ICAL.</li> </ol> </li> <li>See Table 9, "Register Locations Requiring ICAL," on page 63 for register changes that require an ICAL.</li> </ol>
5:0	Reserved	Reserved.

# Register 138.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name		Reserved					LOS2_EN [1:1]	LOS1_EN [1:1]
Туре		R					R/W	R/W

Bit	Name	Function
7:2	Reserved	Reserved.
1	LOS2_EN [1:0]	Enable CKIN2 LOS Monitoring on the Specified Input (2 of 2).  Note: LOS2_EN is split between two registers.  00: Disable LOS monitoring  01: Reserved  10: Enable LOSA monitoring  11: Enable LOS monitoring  LOSA is a slower and less sensitive version of LOS. SEe the Si53xx Family Reference Manual for details.
0	LOS1_EN [1:0]	Enable CKIN1 LOS Monitoring on the Specified Input (1 of 2).  Note: LOS1_EN is split between two registers.  00: Disable LOS monitoring  01: Reserved  10: Enable LOSA monitoring  11: Enable LOS monitoring  LOSA is a slower and less sensitive version of LOS. See the Si53xx Family Reference Manual for details.

# Register 139.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Rese	erved	LOS2_EN [0:0]	LOS1_EN [0:0]	Rese	erved	FOS2_EN	FOS1_EN
Туре	R		R/W	R/W	F	₹	R/W	R/W

Reset value = 1111 1111

Bit	Name	Function
7:6	Reserved	Reserved.
5	LOS2_EN [1:0]	Enable CKIN2 LOS Monitoring on the Specified Input (2 of 2).  Note: LOS2_EN is split between two registers.  00: Disable LOS monitoring  01: Reserved  10: Enable LOSA monitoring  11: Enable LOS monitoring  LOSA is a slower and less sensitive version of LOS. See the Si53xx Family Reference Manual for details
4	LOS1_EN [1:0]	Enable CKIN1 LOS Monitoring on the Specified Input (1 of 2).  Note: LOS1_EN is split between two registers.  00: Disable LOS monitoring  01: Reserved  10: Enable LOSA monitoring  11: Enable LOS monitoring  LOSA is a slower and less sensitive version of LOS. See the Si53xx Family Reference Manual for details.
3:2	Reserved	Reserved.
1	FOS2_EN	Enables FOS on a Per Channel Basis.  0: Disable FOS monitoring  1: Enable FOS monitoring
0	FOS1_EN	Enables FOS on a Per Channel Basis.  0: Disable FOS monitoring  1: Enable FOS monitoring

# Register 142.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name		INDEPENDENTSKEW1 [7:0]						
Туре				R/	W			

Reset value = 0000 0000

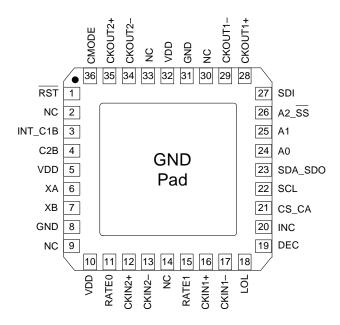
Bit	Name	Function
7:0	ENTSKEW1	INDEPENDENTSKEW1.  Eight-bit field that represents a 2's complement of the phase offset in terms of clocks from the high speed output divider.

# Register 143.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name		INDEPENDENTSKEW2 [7:0]						
Туре				R/	W			

Bit	Name	Function
7:0	ENTSKEW2	INDEPENDENTSKEW2.  Eight-bit field that represents a 2's complement of the phase offset in terms of clocks from the high speed output divider.

# 7. Pin Descriptions: Si5326



Pin #	Pin Name	I/O	Signal Level	Description
1	RST	I	LVCMOS	External Reset.
				Active low input that performs external hardware reset of device. Resets all internal logic to a known state and forces the device registers to their default value. Clock outputs are tristated during reset. The part must be programmed after a reset or power on to get a clock output. See the Si53xx Family Reference Manual for details. This pin has a weak pull-up.
2, 9, 14,	NC		_	No Connection.
30, 33				Leave floating. Make no external connections to this pin for normal operation.
3	INT_C1B	0	LVCMOS	Interrupt/CKIN1 Invalid Indicator.
				This pin functions as a device interrupt output or an alarm output for CKIN1. If used as an interrupt output, <i>INT_PIN</i> must be set to 1. The pin functions as a maskable interrupt output with active polarity controlled by the <i>INT_POL</i> register bit.
				If used as an alarm output, the pin functions as a LOS (and optionally FOS) alarm indicator for CKIN1. Set <i>CK1_BAD_PIN</i> = 1 and <i>INT_PIN</i> = 0.
				0 = CKIN1 present
				1 = LOS (FOS) on CKIN1
				The active polarity is controlled by <i>CK_BAD_POL</i> . If no function is selected, the pin tristates.

Note: Internal register names are indicated by underlined italics, e.g., INT\_PIN. See Section "5.Register Map".

itors should be associated with the following $V_{DD}$ pins: 5 0.1 $\mu F$ 10 0.1 $\mu F$ 32 0.1 $\mu F$	Pin #	Pin Name	I/O	Signal Level	Description
CKIN2 if CK2_BAD_PIN=1.   0 = CKIN2 present     1 = LOS (FOS) on CKIN2     The active polarity can be changed by CK_BAD_POL If CK2_BAD_PIN=0, the pin tristates.   5, 10, 32   VDD   VDD   Supply     Supply   The device operates from a 1.8, 2.5, or 3.3 V supply. Bypass capacitors should be associated with the following VDD pins:     5	4	C2B	0	LVCMOS	CKIN2 Invalid Indicator.
The device operates from a 1.8, 2.5, or 3.3 V supply. Bypass capacitors should be associated with the following V <sub>DD</sub> pins:  5 0.1 µF 10 0.1 µF 32 0.1 µF A 1.0 µF should also be placed as close to the device as is practical.  7 XB 6 XA  8 I Analog External Crystal or Reference Clock. External crystal should be connected to these pins to use internal oscillator based reference. Refer to the Si53xx Family Reference Manual for interfacing to an external reference. External reference must be from a high-quality clock source (TCXO, OCXO). Frequency of crystal or external clock is set by RATE[1:0] pins.  8, 31 GND GND Supply Ground. Must be connected to system ground. Minimize the ground path impedance for optimal performance of this device. Grounding these pins does not eliminate the requirement to ground the GND PAD on the bottom of the package.  11 RATE0 RATE1 External Crystal or Reference Clock Rate. Three level inputs that select the type and rate of external crystal or reference clock to be applied to the XAVXB port. Refer to the Si53xx Family Reference Manual for settings. These pins have both a weak pull-up and a weak pull-down; they default to M. L setting corresponds to VpD. Note: Tying the corresponding Rate <sub>n</sub> pins to HH (V <sub>DD</sub> ) provides compatibility to Si5325. Refer to Si5325 data sheet for operating in this mode. Some designs may require an external resistor voltage divider when driven by an active device that will tristate.  16 CKIN1+ 17 CKIN1- Differential input clock. This input can also be driven with a single-ended signal. Input frequency range is 2 kHz to 710 MHz.  12 CKIN2+ Differential input clock. This input can also be driven with a single-ended signal. Input frequency range is 2 kHz to 710 MHz.					CKIN2 if CK2_BAD_PIN = 1.  0 = CKIN2 present  1 = LOS (FOS) on CKIN2  The active polarity can be changed by CK_BAD_POL. If
External crystal should be connected to these pins to use internal oscillator based reference. Refer to the Si53xx Family Reference Manual for interfacing to an external reference. External reference must be from a high-quality clock source (TCXO, OCXO). Frequency of crystal or external clock is set by RATE[1:0] pins.  8, 31 GND GND Supply Ground.  Must be connected to system ground. Minimize the ground path impedance for optimal performance of this device. Grounding these pins does not eliminate the requirement to ground the GND PAD on the bottom of the package.  11 RATE0 RATE1 External Crystal or Reference Clock Rate.  Three level inputs that select the type and rate of external crystal or reference clock to be applied to the XA/XB port. Refer to the Si53xx Family Reference Manual for settings. These pins have both a weak pull-up and a weak pull-down; they default to M. L setting corresponds to ground.  M setting corresponds to V <sub>DD</sub> /2.  H setting corresponds to V <sub>DD</sub> /2.  H setting corresponds to V <sub>DD</sub> /2.  Note: Tying the corresponding Rate <sub>n</sub> pins to HH (V <sub>DD</sub> ) provides compatibility to Si5325. Refer to Si5325 data sheet for operating in this mode.  Some designs may require an external resistor voltage divider when driven by an active device that will tristate.  Clock Input 1.  Differential input clock. This input can also be driven with a single-ended signal. Input frequency range is 2 kHz to 710 MHz.  Clock Input 2.  Differential input clock. This input can also be driven with a single-	5, 10, 32	V <sub>DD</sub>	V <sub>DD</sub>	Supply	The device operates from a 1.8, 2.5, or 3.3 V supply. Bypass capacitors should be associated with the following $V_{DD}$ pins: 5 0.1 $\mu F$ 10 0.1 $\mu F$
Must be connected to system ground. Minimize the ground path impedance for optimal performance of this device. Grounding these pins does not eliminate the requirement to ground the GND PAD on the bottom of the package.  11 RATE0 I 3-Level External Crystal or Reference Clock Rate.  Three level inputs that select the type and rate of external crystal or reference clock to be applied to the XA/XB port. Refer to the Si53xx Family Reference Manual for settings. These pins have both a weak pull-up and a weak pull-down; they default to M. L setting corresponds to ground. M setting corresponds to V <sub>DD</sub> /2. H setting corresponds to V <sub>DD</sub> /2. Note: Tying the corresponding Rate <sub>n</sub> pins to HH (V <sub>DD</sub> ) provides compatibility to Si5325. Refer to Si5325 data sheet for operating in this mode. Some designs may require an external resistor voltage divider when driven by an active device that will tristate.  16 CKIN1+ I Multi Clock Input 1. Differential input clock. This input can also be driven with a single-ended signal. Input frequency range is 2 kHz to 710 MHz.  12 CKIN2+ I Multi Clock Input 2. Differential input clock. This input can also be driven with a single-			I	Analog	External crystal should be connected to these pins to use internal oscillator based reference. Refer to the Si53xx Family Reference Manual for interfacing to an external reference. External reference must be from a high-quality clock source (TCXO, OCXO). Fre-
Three level inputs that select the type and rate of external crystal or reference clock to be applied to the XA/XB port. Refer to the Si53xx Family Reference Manual for settings. These pins have both a weak pull-up and a weak pull-down; they default to M.  L setting corresponds to ground.  M setting corresponds to V <sub>DD</sub> /2.  H setting corresponding Rate <sub>n</sub> pins to HH (V <sub>DD</sub> ) provides compatibility to Si5325. Refer to Si5325 data sheet for operating in this mode.  Some designs may require an external resistor voltage divider when driven by an active device that will tristate.  16 CKIN1+ I Multi Clock Input 1.  Differential input clock. This input can also be driven with a single-ended signal. Input frequency range is 2 kHz to 710 MHz.  12 CKIN2+ I Multi Clock Input 2.  Differential input clock. This input can also be driven with a single-ended signal input clock. This input can also be driven with a single-ended signal.	8, 31	GND	GND	Supply	Must be connected to system ground. Minimize the ground path impedance for optimal performance of this device. Grounding these pins does not eliminate the requirement to ground the GND PAD on
Three level inputs that select the type and rate of external crystal or reference clock to be applied to the XA/XB port. Refer to the Si53xx Family Reference Manual for settings. These pins have both a weak pull-up and a weak pull-down; they default to M.  L setting corresponds to ground.  M setting corresponds to V <sub>DD</sub> /2.  H setting corresponding Rate <sub>n</sub> pins to HH (V <sub>DD</sub> ) provides compatibility to Si5325. Refer to Si5325 data sheet for operating in this mode.  Some designs may require an external resistor voltage divider when driven by an active device that will tristate.  16 CKIN1+ I Multi Clock Input 1.  Differential input clock. This input can also be driven with a single-ended signal. Input frequency range is 2 kHz to 710 MHz.  12 CKIN2+ I Multi Clock Input 2.  Differential input clock. This input can also be driven with a single-ended signal input clock. This input can also be driven with a single-ended signal.	11	RATE0	I	3-Level	External Crystal or Reference Clock Rate.
16 CKIN1+ I Multi Clock Input 1. 17 CKIN1- Differential input clock. This input can also be driven with a single-ended signal. Input frequency range is 2 kHz to 710 MHz.  12 CKIN2+ I Multi Clock Input 2. 13 CKIN2- Differential input clock. This input can also be driven with a single-					Three level inputs that select the type and rate of external crystal or reference clock to be applied to the XA/XB port. Refer to the Si53xx Family Reference Manual for settings. These pins have both a weak pull-up and a weak pull-down; they default to M. L setting corresponds to ground. M setting corresponds to V <sub>DD</sub> /2. H setting corresponds to V <sub>DD</sub> .  Note: Tying the corresponding Rate <sub>n</sub> pins to HH (V <sub>DD</sub> ) provides compatibility to Si5325. Refer to Si5325 data sheet for operating in this mode.  Some designs may require an external resistor voltage divider when
Differential input clock. This input can also be driven with a single-ended signal. Input frequency range is 2 kHz to 710 MHz.  CKIN2+ I Multi Clock Input 2. CKIN2- Differential input clock. This input can also be driven with a single-			_		-
13 CKIN2- Differential input clock. This input can also be driven with a single-			I	Multi	Differential input clock. This input can also be driven with a single-
13 CKIN2- Differential input clock. This input can also be driven with a single-	12	CKIN2+	I	Multi	Clock Input 2.
					Differential input clock. This input can also be driven with a single-

Pin #	Pin Name	I/O	Signal Level	Description
18	LOL	0	LVCMOS	PLL Loss of Lock Indicator.  This pin functions as the active high PLL loss of lock indicator if the LOL_PIN register bit is set to 1.  0 = PLL locked  1 = PLL unlocked  If LOL_PIN = 0, this pin will tristate. Active polarity is controlled by the LOL_POL bit. The PLL lock status will always be reflected in the LOL_INT read only register bit.
19	DEC	I	LVCMOS	Skew Decrement.  A pulse on this pin decreases the input to output device skew by 1/f <sub>OSC</sub> (approximately 200 ps). There is no limit on the range of skew adjustment by this method.  Pin control is enabled by setting INCDEC_PIN = 1. If INCDEC_PIN = 0, this pin is ignored and output skew is controlled via the CLAT register.  If both INC and DEC are tied high, phase buildout is disabled and the device maintains a fixed-phase relationship between the selected input clock and the output clock during an input clock switch.  See the Si53xx Family Reference Manual for more details.  This pin has a weak pull-down.
20	INC	mas ar	LVCMOS	Skew Increment.  A pulse on this pin increases the input to output device skew by 1/f <sub>OSC</sub> (approximately 200 ps). There is no limit on the range of skew adjustment by this method.  Pin control is enabled by setting INCDEC_PIN = 1. If INCDEC_PIN = 0, this pin is ignored and output skew is controlled via the CLAT register.  If both INC and DEC are tied high, phase buildout is disabled and the device maintains a fixed-phase relationship between the selected input clock and the output clock during an input clock switch.  See the Si53xx Family Reference Manual for more details.  Note: INC does not increase skew if NI_HS = 4.  This pin has a weak pull-down.  derlined italics, e.g., INT_PIN. See Section "5.Register Map".

Pin#	Pin Name	I/O	Signal Level	Description
21	CS_CA	I/O	LVCMOS	Input Clock Select/Active Clock Indicator.
				Input: In manual clock selection mode, this pin functions as the manual input clock selector if the <i>CKSEL_PIN</i> is set to 1.  0 = Select CKIN1  1 = Select CKIN2  If <i>CKSEL_PIN</i> = 0, the <i>CKSEL_REG</i> register bit controls this function and this input tristates. If configured for input, must be tied high or low.  Output: In automatic clock selection mode, this pin indicates which of the two input clocks is currently the active clock. If alarms exist or both clocks, CK_ACTV will indicate the last active clock that was used before entering the digital hold state. The <i>CK_ACTV_PIN</i> register bit must be set to 1 to reflect the active clock status to the CK_ACTV output pin.  0 = CKIN1 active input clock  1 = CKIN2 active input clock  If <i>CK_ACTV_PIN</i> = 0, this pin will tristate. The CK_ACTV status wire always be reflected in the <i>CK_ACTV_REG</i> read only register bit.
22	SCL	ı	LVCMOS	Serial Clock.
22	SOL	'	LVCIVIOS	This pin functions as the serial clock input for both SPI and I <sup>2</sup> C modes.  This pin has a weak pull-down.
23	SDA_SDO	I/O	LVCMOS	Serial Data.  In I <sup>2</sup> C control mode (CMODE = 0), this pin functions as the bidirectional serial data port.  In SPI control mode (CMODE = 1), this pin functions as the serial data output.
25	A1	I	LVCMOS	Serial Port Address.
24	A0			In $I^2C$ control mode (CMODE = 0), these pins function as hardward controlled address bits. The $I^2C$ address is 1101 [A2] [A1] [A0]. In SPI control mode (CMODE = 1), these pins are ignored. These pins have a weak pull-down.
26	A2_SS	I	LVCMOS	Serial Port Address/Slave Select.  In I <sup>2</sup> C control mode (CMODE = 0), this pin functions as a hardware controlled address bit [A2].  In SPI control mode (CMODE = 1), this pin functions as the slave select input.  This pin has a weak pull-down.
27	SDI	I	LVCMOS	Serial Data In.  In I <sup>2</sup> C control mode (CMODE = 0), this pin is ignored.  In SPI control mode (CMODE = 1), this pin functions as the serial data input.  This pin has a weak pull-down.

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Pin #	Pin Name	I/O	Signal Level	Description
29	CKOUT1-	0	Multi	Output Clock 1.
28	CKOUT1+			Differential output clock with a frequency range of 2 kHz to 1.4 GHz. Output signal format is selected by <i>SFOUT1_REG</i> register bits. Output is differential for LVPECL, LVDS, and CML compatible modes. For CMOS format, both output pins drive identical single-ended clock outputs.
34	CKOUT2-	0	Multi	Output Clock 2.
35	CKOUT2+			Differential output clock with a frequency range of 2 kHz to 1.4 GHz. Output signal format is selected by <i>SFOUT2_REG</i> register bits. Output is differential for LVPECL, LVDS, and CML compatible modes. For CMOS format, both output pins drive identical single-ended clock outputs.
36	CMODE	I	LVCMOS	Control Mode.  Selects $I^2C$ or SPI control mode for the Si5326. $0 = I^2C$ Control Mode  1 = SPI Control Mode  This pin must not be NC. Tie either high or low.  See the Si53xx Family Reference Manual for details on $I^2C$ or SPI operation.
				Ground Pad.
GND PAD	GND	GND	Supply	The ground pad must provide a low thermal and electrical impedance to a ground plane.
Note: Inter	nal register na			, ,

Table 9 lists all of the register locations that should be followed by an ICAL after their contents are changed.

**Table 9. Register Locations Requiring ICAL** 

Addr	Register	
0	BYPASS_REG	
0	CKOUT_ALWAYS_ON	
1	CK_PRIOR2	
1	CK_PRIOR1	
2	BWSEL_REG	
4	HIST_DEL	
5	ICMOS	
7	FOSREFSEL	
9	HIST_AVG	
10	DSBL2_REG	
10	DSBL1_REG	
11	PD_CK2	
11	PD_CK1	
19	FOS_EN	
19	FOS_THR	
19	VALTIME	
19	LOCKT	
21	INCDEC_PIN	
25	N1_HS	
31	NC1_LS	
34	NC2_LS	
40	N2_HS	
40	N2_LS	
43	N31	
46	N32	
55	CLKIN2RATE	
55	CLKIN1RATE	

Table 10. Si5326 Pull up/Pull down

Pin #	Si5326	Pull up/ Pull down
1	RST	U
11	RATE0	U, D
15	RATE1	U, D
19	DEC	D
20	INC	D
21	CS_CA	U, D
22	SCL	D
24	A0	D
25	A1	D
26	A2_SS	D
27	SDI	D
36	CMODE	U, D

# 8. Ordering Guide

Ordering Part Number	Output Clock Frequency Range	Package	ROHS6, Pb-Free	Temperature Range	
Si5326A-C-GM	2 kHz-945 MHz 970-1134 MHz 1.213-1.4 GHz	36-Lead 6 x 6 mm QFN	Yes	−40 to 85 °C	
Si5326B-C-GM	2 kHz-808 MHz	36-Lead 6 x 6 mm QFN	Yes	–40 to 85 °C	
Si5326C-C-GM	2 kHz-346 MHz	36-Lead 6 x 6 mm QFN	Yes	–40 to 85 °C	
Si5325/26-EVB		Evaluation Board			
Note: Add an R at the end of the device to denote tape and reel options.					

# 9. Package Outline: 36-Pin QFN

Figure 7 illustrates the package details for the Si5326. Table 11 lists the values for the dimensions shown in the illustration.

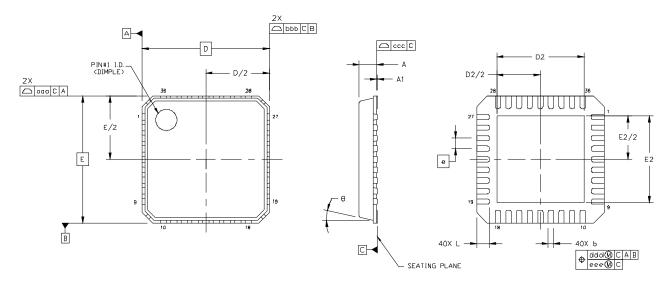


Figure 7. 36-Pin Quad Flat No-lead (QFN)

**Table 11. Package Dimensions** 

Symbol	Millimeters				
	Min	Nom	Max		
Α	0.80	0.85	0.90		
A1	0.00	0.02	0.05		
b	0.18	0.25	0.30		
D		6.00 BSC			
D2	3.95	4.10	4.25		
е		0.50 BSC			
Е	6.00 BSC				
E2	3.95	4.10	4.25		

Symbol	Millimeters				
	Min	Nom	Max		
L	0.50	0.60	0.70		
θ	_	_	12º		
aaa	_	_	0.10		
bbb	_	_	0.10		
ccc	_	_	0.08		
ddd	_	_	0.10		
eee	_	_	0.05		

#### Notes:

- 1. All dimensions shown are in millimeters (mm) unless otherwise noted.
- 2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
- 3. This drawing conforms to JEDEC outline MO-220, variation VJJD.
- 4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.

# 10. Recommended PCB Layout

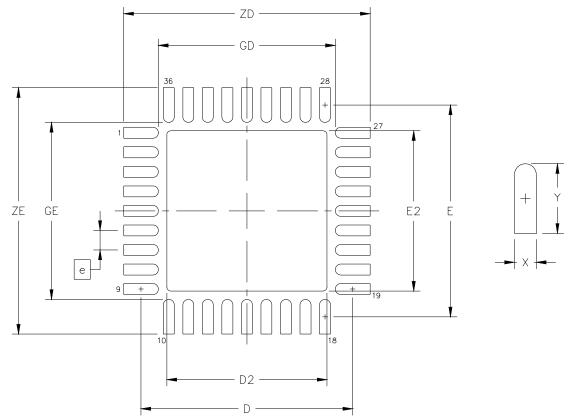


Figure 8. PCB Land Pattern Diagram

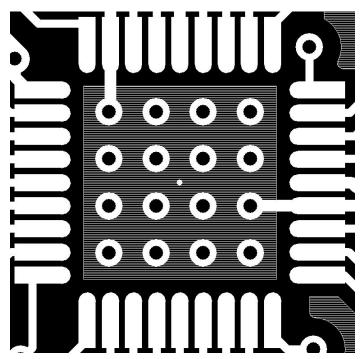


Figure 9. Ground Pad Recommended Layout

**Table 12. PCB Land Pattern Dimensions** 

Dimension	MIN	MAX
е	0.50	BSC.
Е	5.42	REF.
D	5.42	REF.
E2	4.00	4.20
D2	4.00	4.20
GE	4.53	_
GD	4.53	_
Х	_	0.28
Y	0.89	REF.
ZE	_	6.31
ZD	_	6.31

#### Notes (General):

- 1. All dimensions shown are in millimeters (mm) unless otherwise noted.
- 2. Dimensioning and Tolerancing is per the ANSI Y14.5M-1994 specification.
- 3. This Land Pattern Design is based on IPC-SM-782 guidelines.
- **4.** All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm.

#### Notes (Solder Mask Design):

1. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 µm minimum, all the way around the pad.

#### Notes (Stencil Design):

- 1. A stainless steel, laser-cut, and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
- 2. The stencil thickness should be 0.125 mm (5 mils).
- **3.** The ratio of stencil aperture to land pad size should be 1:1 for the perimeter pads.
- **4.** A 4 x 4 array of 0.80 mm square openings on 1.05 mm pitch should be used for the center ground pad.

#### Notes (Card Assembly):

- 1. A No-Clean, Type-3 solder paste is recommended.
- 2. The recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.

# 11. Si5326 Device Top Mark



Mark Method:	Laser	
Font Size:	0.80 mm Right-Justified	
Line 1 Marking:	Si5326Q	Customer Part Number Q = Speed Code: A, B, C See Ordering Guide for options
Line 2 Marking:	C-GM	C = Product Revision G = Temperature Range -40 to 85 °C (RoHS6) M = QFN Package
Line 3 Marking:	YYWWRF	YY = Year WW = Work Week R = Die Revision F = Internal code Assigned by the Assembly House. Corresponds to the year and work week of the mold date.
Line 4 Marking:	Pin 1 Identifier	Circle = 0.75 mm Diameter Lower-Left Justified
	XXXX	Internal Code

# **DOCUMENT CHANGE LIST**

#### Revision 0.1 to Revision 0.2

- Updated LVTTL to LVCMOS is Table 2, "Absolute Maximum Ratings," on page 6.
- Added Figure 3, "Typical Phase Noise Plot," on page 16.
- Updated Figure 4, "Si5326 Typical Application Circuit (I<sup>2</sup>C Control Mode)," and Figure 5, "Si5326 Typical Application Circuit (SPI Control Mode)," on page 17 to show preferred external reference interface.
- Updated "5.Register Map".
  - Added RATE0 and changed RATE to RATE1 and expanded RATE[1:0] description.
  - Changed font of register names to underlined italics.
- Updated "8. Ordering Guide" on page 65.
- Added "9. Package Outline: 36-Pin QFN" on page 66.
- Added "10.Recommended PCB Layout".

#### Revision 0.2 to Revision 0.3

- Changed 1.8 V operating range to ±5%.
- Updated Table 1 on page 4.
- Updated Table 2 on page 6.
- Updated Table 11 on page 66.
- Added table under Figure 3 on page 16.
- Updated "4. Functional Description" on page 18.
- Clarified "5. Register Map" on page 20 including pullup/pull-down.

#### Revision 0.3 to Revision 0.4

- Updated Table 1 on page 4.
- Added "11. Si5326 Device Top Mark" on page 69.

#### Revision 0.4 to Revision 0.41

- Changed "latency" to "skew" throughout.
- Updated Table 1 on page 4.
  - Updated Thermal Resistance Junction to Ambient typical specification.
- Updated Figure 4 on page 17.
- Updated Figure 5, "Si5326 Typical Application Circuit (SPI Control Mode)," on page 17.
- Updated "5. Register Map" on page 20.
- Updated "9. Package Outline: 36-Pin QFN" on page 66.
- Added Figure 9, "Ground Pad Recommended Layout," on page 67
- Added Register Map

#### Revision 0.41 to Revision 0.42

■ Text added to section "5. Register Map" on page 20.

#### Revision 0.42 to Revision 0.43

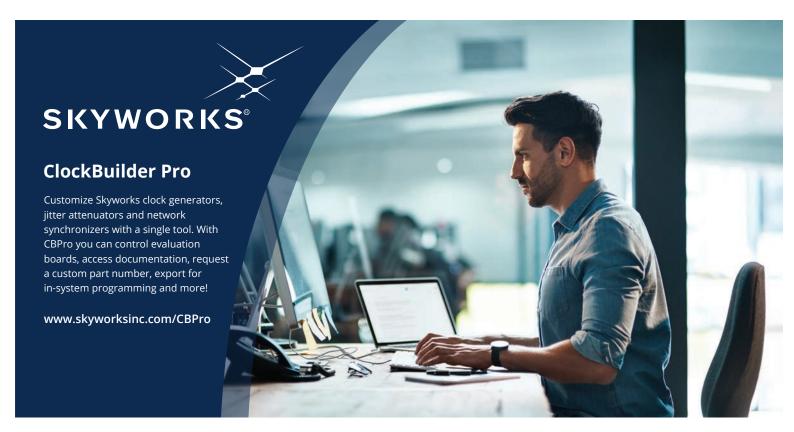
- Replaced Figure 9.
- Updated Rise/Fall time values.

#### Revision 0.43 to Revision 0.44

Changed register address labels to decimal.

#### **Revision 0.44 to Revision 1.0**

- Updated first page format to add chip image and pin out
- Updated Functional Block Diagram.
- Updated Section "1.Electrical Specifications" to include ac/dc specifications from the Si53xx Family Reference Manual (FRM).
- Updated typical phase noise performance in Section "2.Typical Phase Noise Performance".
- Added INC/DEC pins to Figure 4 and Figure 5
- Clarified the format for FLAT [14:0].
- Added list of weak pull up/down resistors in Table 10, "Si5326 Pull up/Pull down," on page 64.
- Updated register maps 19, 20, 46, 47, 55, 142, 143, 185.
- Added note to typical application circuits in Section "3.Typical Application Circuit"
- Added evaluation board part number to "8.Ordering Guide".
- Updated Section "11.Si5326 Device Top Mark"
- Updated Table 5, "Jitter Generation," on page 14; filled in all TBDs, and lowered typical RMS values.









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